INTEGRATED CIRCUIT DIE WITH DIRECTLY COUPLED NOISE SUPPRESSION AND/OR OTHER DEVICE

ABSTRACT OF THE DISCLOSURE

An integrated circuit die (20,120,220) having EMI suppression and/or other devices (50-54,150,155-159,250) surface mounted thereon. EMI suppression devices such as capacitors are disclosed that are direct chip attach mounted to integrated circuit dies through vias to the redistribution layers (30,130,230) or through vias directly to the circuitry (24,124). Similarly mounted or otherwise provided resistors, inductors and other circuit devices (50-54,150,155-159,200) are also disclosed.

Figure 1



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